

1 ABSTRACT OF THE DISCLOSURE

740 A, / A device includes a chip, and a resin
package sealing the chip, the resin package having
resin projections located on a mount-side surface of
5 the resin package. Metallic films are respectively
provided to the resin projections. Connecting parts
electrically connect electrode pads of the chip and
the metallic films.

10

15

20

25

30